



SOT449-1

plastic small outline package; 40 leads (J-bent); body width
10.16 mm

6 September 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOJ40
Package type industry code	SOJ40
Package style descriptive code	SOJ
Package body material type	P (plastic)
JEDEC package outline code	MS-027
Mounting method type	S (surface mount)
Issue date	18-2-2003

Table 1. Package summary

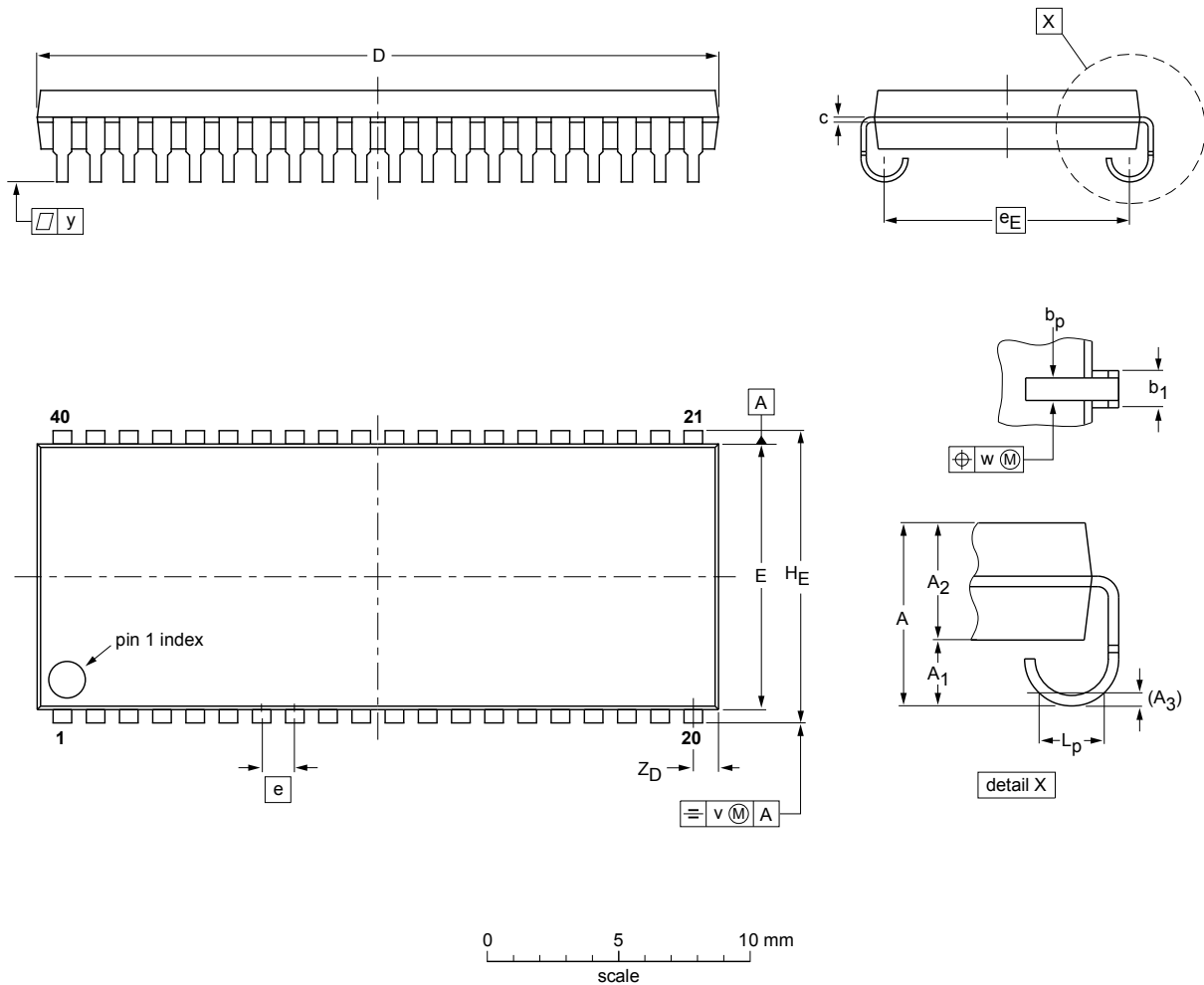
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	25.9	-	26.05	26.2	mm
E	package width	10	-	10.16	10.3	mm
A	seated height	-	-	3.68	3.68	mm
A ₂	package height	2.18	-	2.235	2.29	mm
n ₂	actual quantity of termination	-	-	40	-	



2. Package outline

SOJ40: plastic small outline package; 40 leads (J-bent); body width 10.16 mm

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DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e _E	H _E	L _p	v	w	y	Z _D ⁽¹⁾
mm	3.68	1.40 1.14	2.29 2.18	0.25	0.51 0.38	0.81 0.66	0.32 0.18	26.2 25.9	10.3 10.0	1.27	9.4	11.30 11.05	1.4 1.1	0.18	0.18	0.1	1.19 0.73

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT449-1		MS-027				-99-12-27- 03-02-18

Fig. 1. Package outline SOJ40 (SOT449-1)

3. Soldering

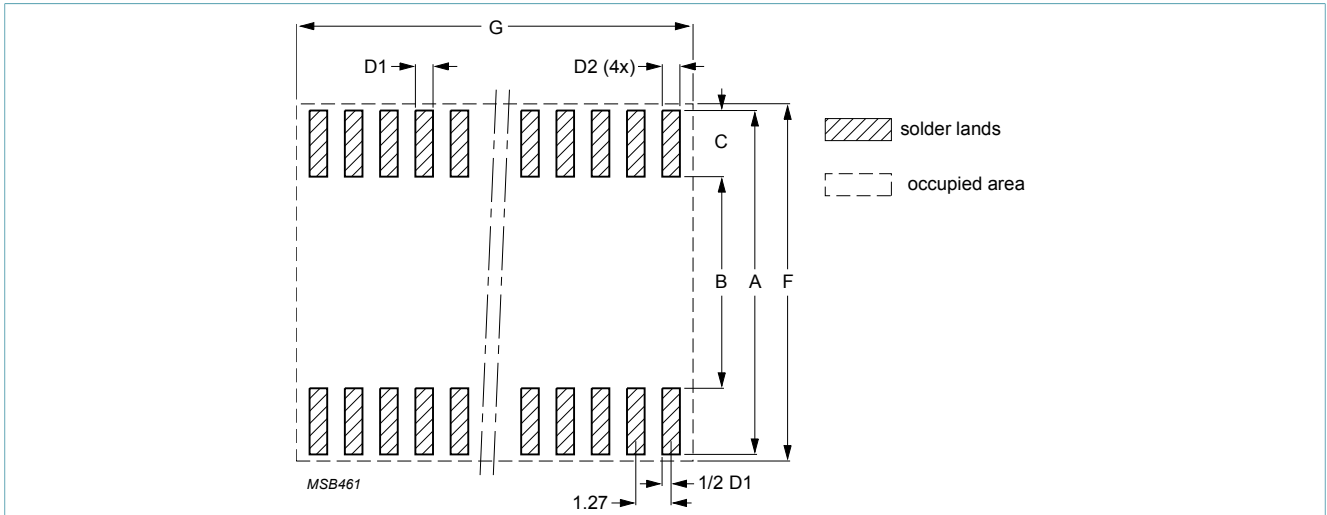


Fig. 2. Reflow soldering footprint for SOJ40 (SOT449-1)

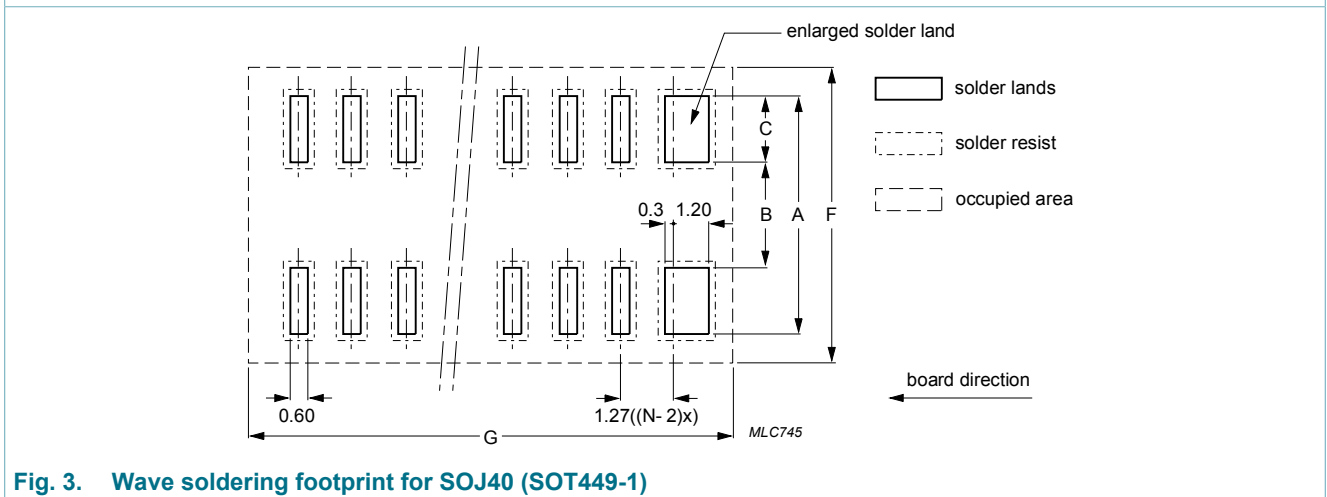


Fig. 3. Wave soldering footprint for SOJ40 (SOT449-1)

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